

ABSTRACT

SURFACE-TREATED COPPER FOIL

[Abstract] Provided is a surface-treated copper foil, wherein a plated layer essentially consisting of cobalt and nickel, in which a total amount of cobalt and nickel is $75 \mu\text{g}/\text{dm}^2$ or more and $200 \mu\text{g}/\text{dm}^2$ or less and Co/Ni is 1 or more and 3 or less, is provided on the roughened surface of a copper foil. The present invention aims to form a surface-treated copper foil, which has superior alkali etching properties and maintains favorable characteristics of hydrochloric acid resistance, heat resistance and weather resistance, and of which the surface takes on a red color.